

客户 Customer: _____

日期 Date: _____

纳入仕様书 Preliminary SPECIFICATION

产品名称 PRODUCT NAME: 耦合器 Coupler
 贵司料号 YOUR PART NO.: _____
 敝司料号 OUR PART NO.: MGMC0605H2450G17-C67
 版本号 VERSION: V1.1

接受 RECEPTION		
公司: COMPANY:		日期: DATE:
批准 CFMD	审核 CHKD	接收 RCVD

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MANUFACTURING NAME

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纳入仕様书改定履历 MODIFY HISTORY OF SPECIFICATION

Ver.	DATE	CONTENT	APPROVED
1.0	2020.5.20	初稿 Constitute	梁启新
1.1	2020.8.20	更新功率容量和拓展带宽 Modify Power Capacity 0.5mW→3W Low Band 2.4GHz~2.5GHz → 2.4GHz~2.69GHz	梁启新

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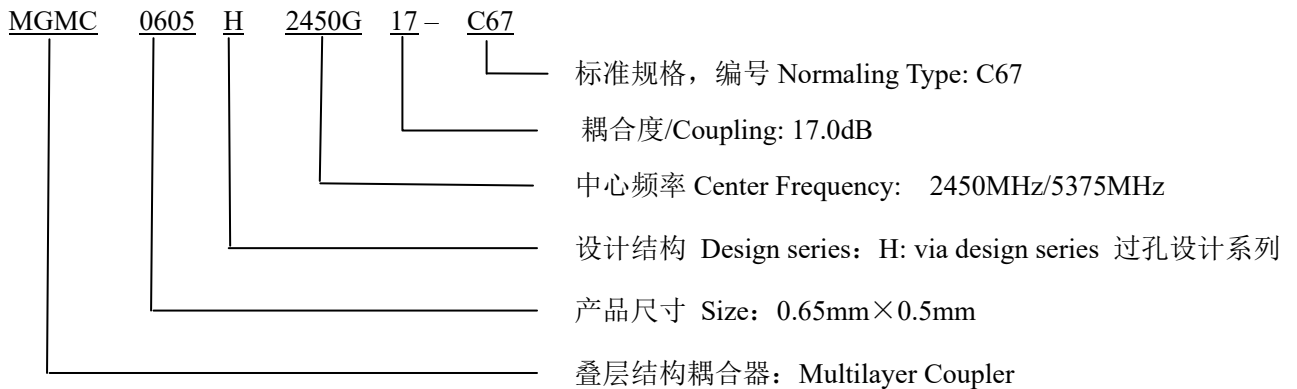
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1 适用范围 Scope

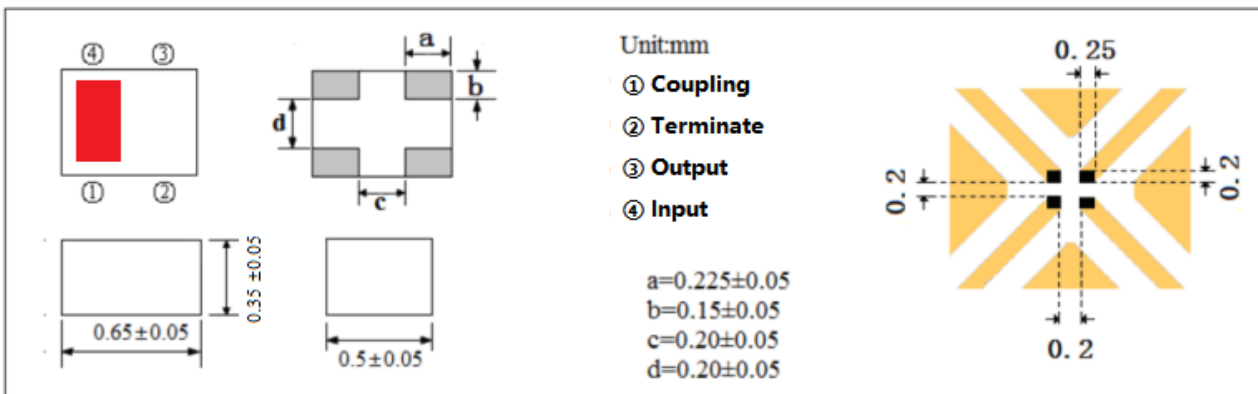
“麦捷”叠层片式耦合器系列产品设计用于 5G、LTE、WIFI、Bluetooth、PDA 和无绳电话机等，具有低的插入损耗、高的隔离度和小体积 SMD 片式设计，能减少复杂的调校工作，可以简化电路设计。

“Microgate” Multilayer chip coupler series are designed to be used in in 5G、LTE、WIFI、Bluetooth、PDA & cordless phones with low insertion loss and high isolation as well as small size SMD chip design , which can simplify your complex tuning and circuit design .

2 品名构成 Product Identification



3 形状、尺寸 Appearance, Dimensions and Material



4 测试条件 Testing Conditions

除非另有规定，否则在以下条件下测试 <Unless otherwise specified>

温度 Temperature : Ordinary Temperature (-40 to +85°C)

湿度 Humidity : Ordinary Humidity (25 to 85% RH)

大气压强 Atmospheric Pressure : 86 to 106 kPa

5 电气性能 Electrical Characteristics

操作温度范围 Operating Temperature Range : -40 to +85°C

保存温度范围 Storage Temperature Range : -40 to +85°C

Item	Specification	
Frequency range	2400 to 2690 MHz	4900 to 5850 MHz
Insertion Loss	0.50 dB max. at +25°C 0.55 dB max. at -40 to +85°C	0.50 dB max. at +25°C 0.55 dB max. at -40 to +85°C
Coupling Factor	19.0 ± 1.5 dB	12.5 ± 1.5 dB
Directivity	15 dB min.	
VSWR	1.3 max.	
Impedance	50 Ω	
Power Capacity	3 W max.	

6 焊接条件 Recommended Soldering Conditions

产品可用于回流焊 Product can be applied to reflow soldering.

(1) 焊剂 Flux, Solder

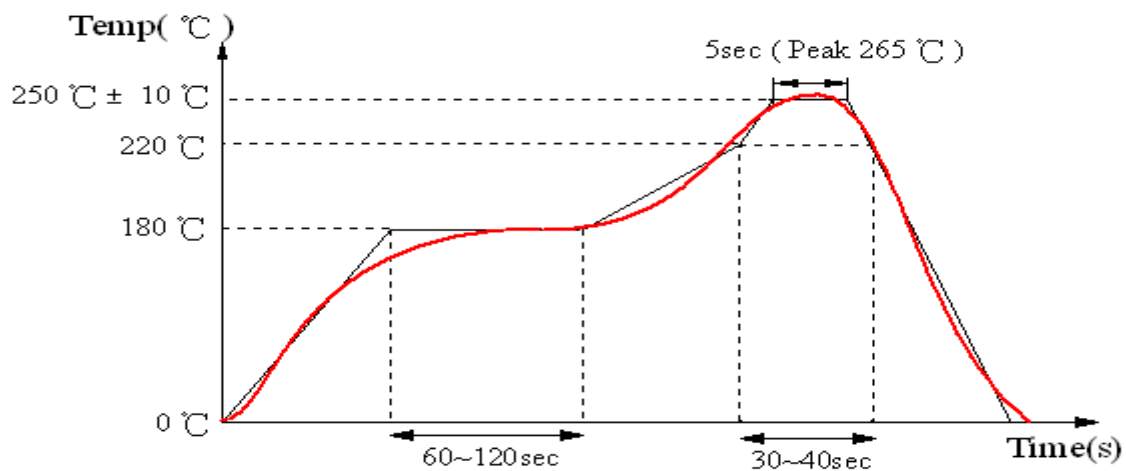
① 使用松香助焊剂，禁止使用卤化物含量超过 0.2wt% 的强酸性助焊剂。

Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).

② 使用纯锡焊料

Use Sn solder.

(2) 标准回流焊曲线 Standard soldering profile.



(3) 手工烙铁手工焊接 Keworking with soldering iron

当使用电烙铁进行手工焊接时，以下条件必须严格遵守 The following conditions must be strictly followed when using a soldering iron.

预热 Pre-heating	150°C, 1 minute
尖端温度 Tip temperature	350°C max
输出功率 Soldering iron output	80w max
电烙铁头尖端尺寸 End of soldering iron	φ3mm max
焊接时间 Soldering time	3 seconds max